

**A PROCESS AND AN INTEGRATED TOOL FOR LOW K DIELECTRIC
DEPOSITION INCLUDING A PECVD CAPPING MODULE****ABSTRACT OF THE DISCLOSURE**

A series of modular apparatuses for processing substrates using a unique combinations of a substrate coating subsystem, a substrate curing subsystem and a PECVD-based capping subsystem. The individual subsystems are capable of being combined with one another for creating unique integrated substrate processing apparatuses that enable combined processing by the coating, curing and capping subsystems in an integrated and controlled environment, thus enabling the processing of substrates in an efficient manner, while minimizing the exposure of the substrates to an external environment and minimizing the condensation of vapors while the substrate is processed by the cure and capping subsystems.

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